

What is claimed is:

1 1. A semiconductor manufacturing device having a mechanical
2 drive part which is moved in a vacuum device while holding a
3 substrate comprising,
4 at least one discharge port for introducing inert gas into
5 said vacuum device, and
6 a flow rate control part for controlling the inert gas which
7 is discharge into said vacuum device from said discharge port
8 at a constant flow rate.

1 2. The semiconductor manufacturing device as claimed in claim
2 1, further comprising an inspection processing part for
3 inspecting said substrate.

1 3. The semiconductor manufacturing device as claimed in claim
2 1, further comprising an exposure processing part for exposing
3 said substrate.

1 4. The semiconductor manufacturing device as claimed in claim
2 1, wherein said discharge port is disposed at a position in the
3 vicinity of the substrate held by said mechanical drive part
4 where it does not make contact with the substrate.

1 5. The semiconductor manufacturing device as claimed in claim
2 1, wherein said mechanical drive part is located between said
3 discharge port and a vacuum exhaust port in said vacuum device.

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1 6. The semiconductor manufacturing device as claimed in claim
2 1, wherein
3 the total evacuation rate of the vacuum pump connected to said
4 vacuum device is more than 300L/s and less than 5,000L/s,
5 the degree of vacuum within said vacuum device is higher than
6 133×10^{-7} kPa and lower than 133×10^{-4} kPa, and
7 the flow rate of said inert gas is more than 0.5cm³/min and less
8 than 20cm³/min.

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